



SSCL085N200GTL

N-Channel Enhancement Mode MOSFET

➤ Features

V_{DS}	V_{GS}	$R_{DS(ON)}$ Typ.	I_D
200V	$\pm 20V$	$8.5m\Omega@10V$	117A

➤ Description

The device is N-Channel enhancement mode MOSFET. Uses SGT Technology and design to provide excellent $R_{DS(ON)}$ with low gate charge. This device is suitable for use in DC - DC conversion, power switch and charging circuit.

100% UIS + ΔV_{DS} + R_g Tested!

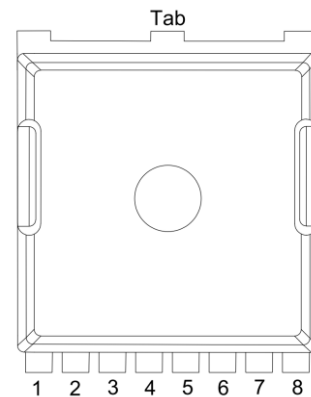
➤ Applications

- Inverter
- DC-DC Converter
- Half and Full Bridge Topology
- Motor Drive Control

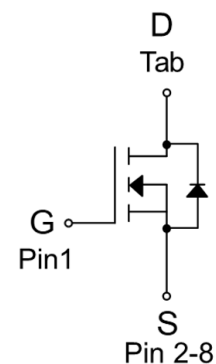
➤ Ordering Information

Device	Package	Shipping
SSCL085N200GTL	TOLL	2000/Reel

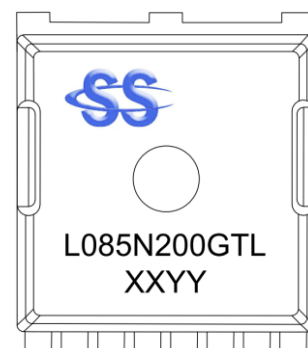
➤ Pin configuration



TOLL (Top View)



Pin Configuration



Marking

(XYYY: Internal Traceability Code)



➤ **Absolute Maximum Ratings ($T_A=25^{\circ}\text{C}$ unless otherwise noted)**

Symbol	Parameter		Ratings	Unit
V_{DS}	Drain-to-Source Voltage		200	V
V_{GS}	Gate-to-Source Voltage		± 20	V
I_D	Continuous Drain Current ^b	$T_C = 25^{\circ}\text{C}$	117	A
		$T_C = 100^{\circ}\text{C}$	74	A
I_{DSM}	Continuous Drain Current ^a	$T_A = 25^{\circ}\text{C}$	11	A
		$T_A = 70^{\circ}\text{C}$	9	A
I_{DM}	Pulsed Drain Current ^b		468	A
P_D	Power Dissipation ^c	$T_C = 25^{\circ}\text{C}$	250	W
		$T_C = 100^{\circ}\text{C}$	100	W
P_{DSM}	Power Dissipation ^a	$T_A = 25^{\circ}\text{C}$	2.3	W
		$T_A = 70^{\circ}\text{C}$	1.5	W
I_{AS}	Avalanche Current ^b $L = 0.5\text{mH}$		67	A
E_{AS}	Avalanche Energy ^b $L = 0.5\text{mH}$		1122	mJ
T_J	Operation junction temperature		-55 to 150	$^{\circ}\text{C}$
T_{STG}	Storage temperature range		-55 to 150	$^{\circ}\text{C}$

➤ **Thermal Resistance Ratings ($T_A=25^{\circ}\text{C}$ unless otherwise noted)**

Symbol	Parameter	Ratings	Max.	Unit
$R_{\theta JA}$	Junction-to-Ambient Thermal Resistance ^a	55	70	$^{\circ}\text{C}/\text{W}$
$R_{\theta JC}$	Junction-to-Case Thermal Resistance	0.5	0.7	

Note:

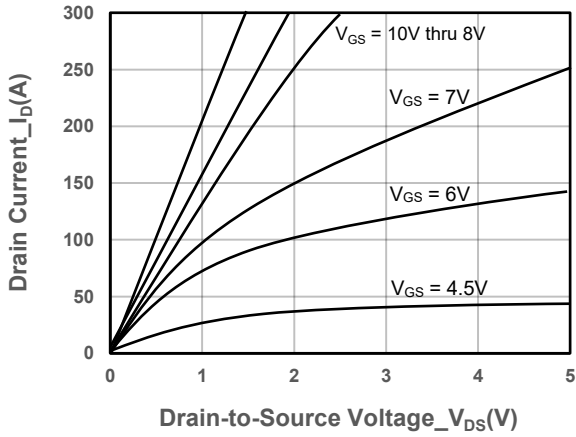
- The value of $R_{\theta JA}$ is measured with the device mounted on 1 in² FR-4 board with 2oz.copper, in a still air environment with $T_A=25^{\circ}\text{C}$. The value in any given application depends on the user's specific board design. The current rating is based on the $t \leq 10\text{s}$ thermal resistance rating.
- Repetitive rating, pulse width limited by junction temperature.
- The power dissipation P_D is based on $T_{J(\text{MAX})}=150^{\circ}\text{C}$, using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heat sinking is used.
- The maximum current rating is package limited.

**➤ Electrical Characteristics (T_A=25°C unless otherwise noted)**

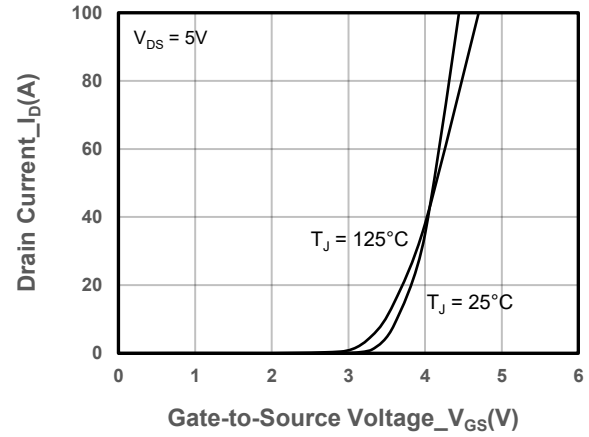
Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Drain-Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} = 0V, I _D = 250μA	200			V
Gate Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = 250uA	2.0	3.0	4.0	V
Drain-Source On-Resistance	R _{DS(on)}	V _{GS} = 10V, I _D = 20A		8.5	11.5	mΩ
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 200V, V _{GS} = 0V			1	μA
Gate-Source Leak Current	I _{GSS}	V _{GS} = ±20V, V _{DS} = 0V			±100	nA
Transconductance	G _{FS}	V _{DS} = 5V, I _D = 20A		100		S
Forward Voltage	V _{SD}	V _{GS} = 0V, I _S = 20A		0.8	1.4	V
Gate Resistance	R _G	V _{DS} = 0V, f = 1MHz		3.5		Ω
Input Capacitance	C _{ISS}	V _{DS} = 100V, V _{GS} = 0V, f = 1MHz		4885		pF
Output Capacitance	C _{OSS}			425		
Reverse Transfer Capacitance	C _{RSS}			25		
Total Gate Charge	Q _G	V _{GS} = 10V, V _{DS} = 100V, I _D = 20A		78		nC
Gate to Source Charge	Q _{GS}			28		
Gate to Drain Charge	Q _{GD}			18		
Turn-on Delay Time	T _{D(ON)}	V _{GS} = 10V, V _{DS} = 100V, I _D = 20A, R _G = 3Ω		24		ns
Rise Time	T _r			45		
Turn-off Delay Time	T _{D(OFF)}			61		
Fall Time	T _f			20		
Diode Recovery Time	T _{rr}	I _F =20A, di/dt=100A/us		132		ns
Diode Recovery Charge	Q _{rr}	I _F =20A, di/dt=100A/us		660		nC



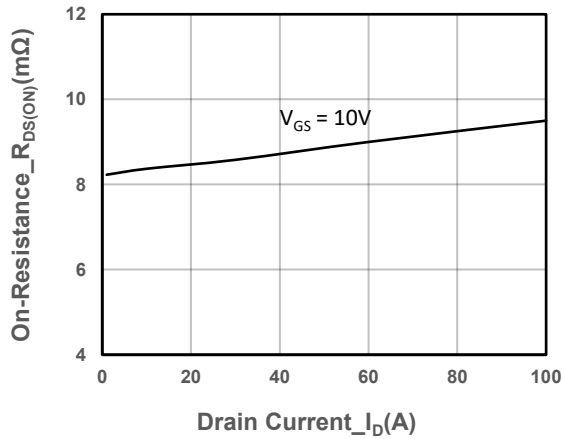
➤ Typical Performance Characteristics ($T_A=25^\circ\text{C}$ unless otherwise noted)



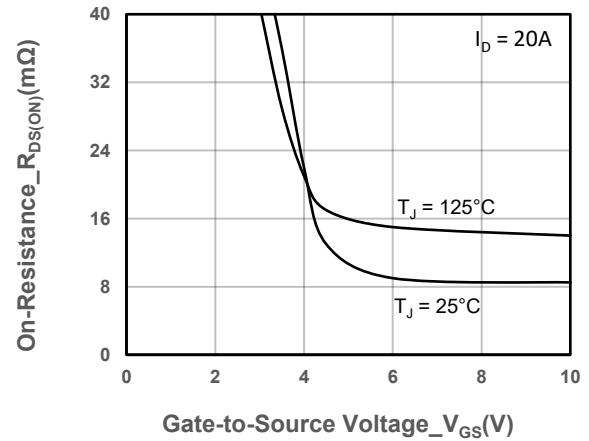
Output Characteristics



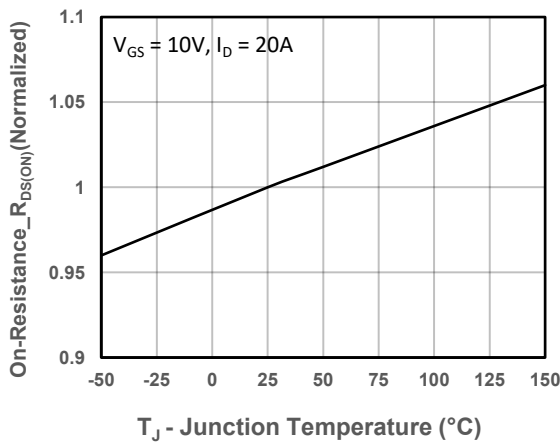
Transfer Characteristics



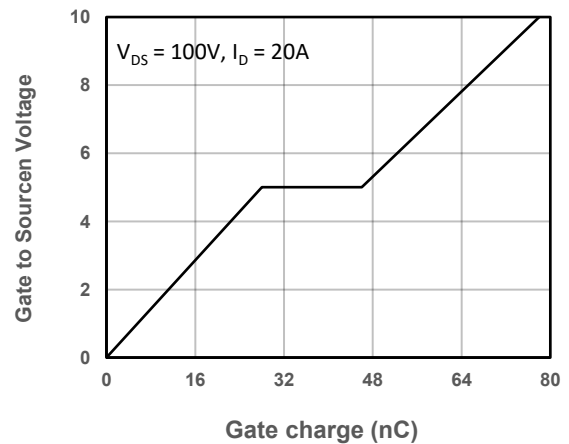
On-Resistance vs. Drain Current and Gate Voltage



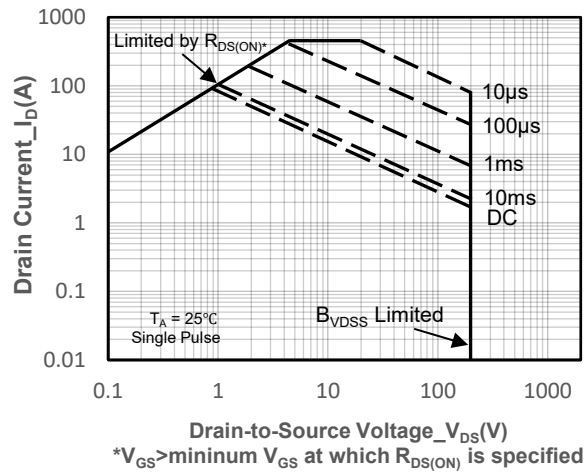
On-Resistance vs. Gate-to-Source Voltage



On-Resistance vs. Junction Temperature



Gate-Source Voltage vs. Gate charge

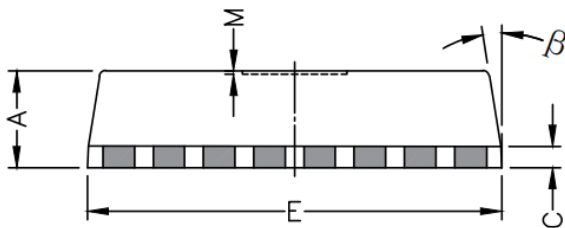
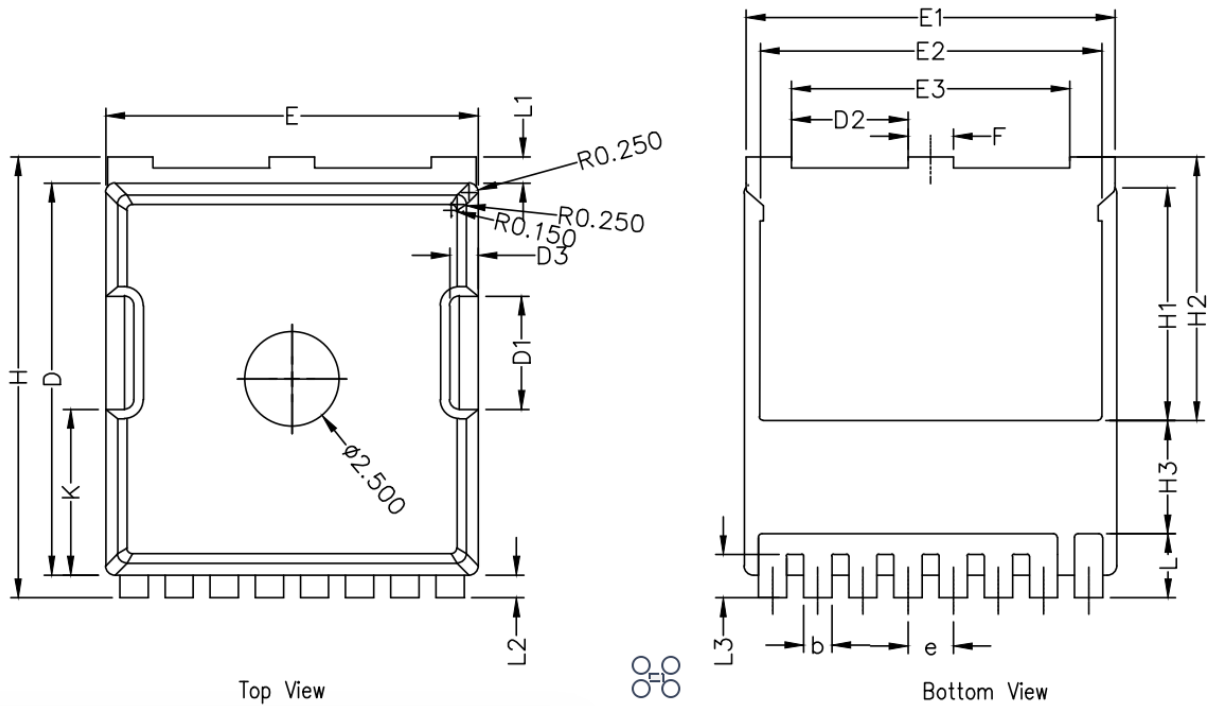


Safe Operating Area vs. Junction-to-Ambient



SSCL085N200GTL

Package Information



Symbols	Millimeters		
	MIN.	NOM.	MAX.
A	2.20	2.30	2.40
b	0.65	0.75	0.85
C	0.508 REF		
D	10.25	10.40	10.55
D1	2.85	3.00	3.15
D2	2.95	3.10	3.25
D3	0.75 REF		
E	9.75	9.90	10.05
E1	9.65	9.80	9.95
E2	8.95	9.10	9.25
E3	7.25	7.40	7.55
e	1.20 BSC		
F	1.05	1.20	1.35
H	11.55	11.70	11.85
H1	6.03	6.18	6.33
H2	6.85	7.00	7.15
H3	3.00 BSC		
L	1.55	1.70	1.85
L1	0.55	0.70	0.85
L2	0.45	0.60	0.75
L3	1.00	1.15	1.30
M	0.08 REF		
β	8°	10°	12°
K	4.25	4.40	4.55



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